



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE2A165		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001729108						
<b>Package</b>		PG-DIP-8-15		<b>Weight*</b>		551.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.846	0.88	0.88	8790	8790
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		97	
	non noble metal	zinc	7440-66-6	0.213	0.04		387	
	non noble metal	iron	7439-89-6	4.266	0.77		7740	
wire	non noble metal	copper	7440-50-8	173.237	31.43	32.25	314279	322503
	noble metal	gold	7440-57-5	0.278	0.05	0.05	504	504
	encapsulation	organic material	carbon black	1333-86-4	1.789	0.32		3246
encapsulation	plastics	epoxy resin	-	48.306	8.76		87634	
	inorganic material	silicondioxide	60676-86-0	307.727	55.83	64.91	558263	649143
leadfinish	non noble metal	tin	7440-31-5	7.496	1.36	1.36	13599	13599
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1453	1453
glue	plastics	epoxy resin	-	0.387	0.07		701	
	noble metal	silver	7440-22-4	1.823	0.33	0.40	3307	4008
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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